[ABSTRACT OF THE DISCLOSURE]

The present invention provides a film for a spacer applied to a multi-chip package and a method of forming a spacer using the same. The film for a spacer according to the present invention includes a first film having a glass transition temperature (Tg) of 130℃ or higher, and an adhesive layer disposed on a lower portion of the first film. The film for a spacer according to the present invention includes the first film instead of a dummy wafer, and has a value of (thermal expansion coefficient/storage modulus) of 1 ppm/GPa to 15 ppm/GPa. Accordingly, it is possible to suppress a die recognition failure occurring in a dicing process and improve pickup ability.

FIG. 5